

General Description

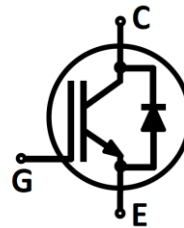
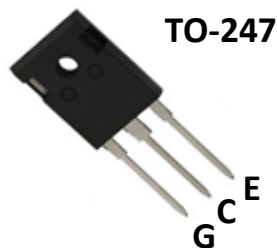
This IGBT is produced using advanced trench fieldstop IGBT technology, which provides low $V_{CE(sat)}$, high switching performance and excellent quality.

Applications

- Welding

Features

- High Speed Switching
- Positive Temperature coefficient for easy paralleling
- High ruggedness&good thermal stability
- Including fast free-wheeling diode
- Very tight parameter distribution



Absolute Maximum Ratings

Characteristics		Symbol	Rating	Unit
Collector-emitter voltage		V_{CE}	1200	V
Gate-emitter voltage		V_{GE}	±20	V
Collector current	$T_C=25^{\circ}\text{C}$	I_C	80	A
	$T_C=100^{\circ}\text{C}$		40	
Pulsed collector current, t_p limited by T_{jmax}		I_{CM}	120	A
Diode forward current @ $T_C=100^{\circ}\text{C}$		I_F	40	A
Diode pulsed collector current, t_p limited by T_{jmax}		I_{FM}	120	A
Short circuit withstand time $V_{GE}=15\text{V}$, $V_{CC}=600\text{V}$, $T_j=25^{\circ}\text{C}$ Allowed number of short circuit < 1000 Time between short circuits $\geq 1.0\text{s}$		t_{SC}	3	μs
Power dissipation	$T_C=25^{\circ}\text{C}$	P_{tot}	297	W
	$T_C=100^{\circ}\text{C}$		119	
Operating junction temperature		T_j	-55~150	$^{\circ}\text{C}$
Storage temperature		T_{stg}	-55~150	

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal resistance junction-to-case for IGBT	R_{thJC}	0.42	°C/W
Thermal resistance junction-to-case for Diode	R_{thJCD}	1.2	
Thermal resistance junction-to-ambient	R_{thJA}	40	

Electrical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Collector-emitter breakdown voltage	BV_{CES}	$V_{GE}=0V, I_C=0.5mA$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=40A$ $T_j=25^\circ\text{C}$	-	2.2	2.4	
		$T_j=150^\circ\text{C}$	-	2.7	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=1.5mA, V_{CE}=V_{GE}$	5	5.8	6.5	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	- -	0.4 4	mA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	200	
Transconductance	g_{FS}	$V_{CE}=20V, I_C=40A$	-	18	-	S
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{CE}=25V$ $V_{GE}=0V$ $f=1MHz$	-	8450	-	pF
Output capacitance	C_{oss}		-	160	-	
Reverse transfer capacitance	C_{rss}		-	120	-	
Gate charge	Q_G	$V_{CC}=750V, I_C=40A$ $V_{GE}=15V$	-	tbd	-	nC

MSG40T120FL

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Switching Characteristics						
Turn-on delay time	$t_{d(on)}$	$T_j=25^{\circ}\text{C}$ $V_{CC}=600\text{V}$ $I_C=40\text{A}$ $V_{GE}=15/0\text{V}$ $R_G=12\Omega$ $L_{load}=500\mu\text{H}$	-	80	-	ns
Rise time	t_r		-	84	-	
Turn-off delay time	$t_{d(off)}$		-	345	-	
Fall time	t_f		-	65	-	
Turn-on switching energy	E_{on}		-	2.6	-	mJ
Turn-off switching energy	E_{off}		-	1.7	-	
Total switching energy	E_{ts}		-	4.3	-	
Turn-on delay time	$t_{d(on)}$	$T_j=150^{\circ}\text{C}$ $V_{CC}=600\text{V}$ $I_C=40\text{A}$ $V_{GE}=15/0\text{V}$ $R_G=12\Omega$ $L_{load}=500\mu\text{H}$	-	70	-	ns
Rise time	t_r		-	77	-	
Turn-off delay time	$t_{d(off)}$		-	410	-	
Fall time	t_f		-	167	-	
Turn-on switching energy	E_{on}		-	2.5	-	mJ
Turn-off switching energy	E_{off}		-	2.9	-	
Total switching energy	E_{ts}		-	5.4	-	
Diode Characteristics						
Forward voltage	V_F	$I_F=40\text{A}, T_j=25^{\circ}\text{C}$	-	3.4	-	V
		$I_F=40\text{A}, T_j=150^{\circ}\text{C}$		2.9	-	
Reverse recovery time	t_{rr}	$T_j=25^{\circ}\text{C}$ $V_R=600\text{V}, I_F=40\text{A}$ $di_F/dt=440\text{A}/\mu\text{s}$	-	60	-	ns
Reverse recovery charge	Q_{rr}		-	0.5	-	μC
Reverse recovery current	I_{rrm}		-	15	-	A
Reverse recovery time	t_{rr}	$T_j=150^{\circ}\text{C}$ $V_R=600\text{V}, I_F=40\text{A}$ $di_F/dt=440\text{A}/\mu\text{s}$	-	143	-	ns
Reverse recovery charge	Q_{rr}		-	1.9	-	μC
Reverse recovery current	I_{rrm}		-	22	-	A

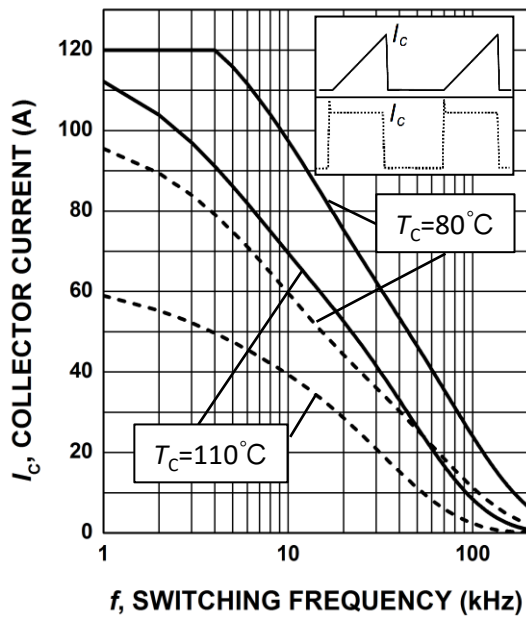


Figure 1. Collector current as a function of switching frequency
 $(T_j \leq 150^\circ\text{C}, D = 0.5, V_{CE} = 600\text{V}, V_{GE} = 0/+15\text{V}, R_G = 12\Omega)$

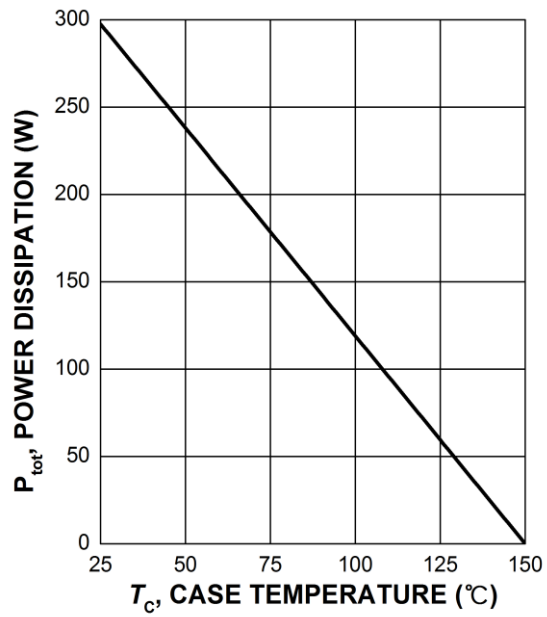


Figure 2. Maximum power dissipation as a function of case temperature
 $(T_j \leq 150^\circ\text{C})$

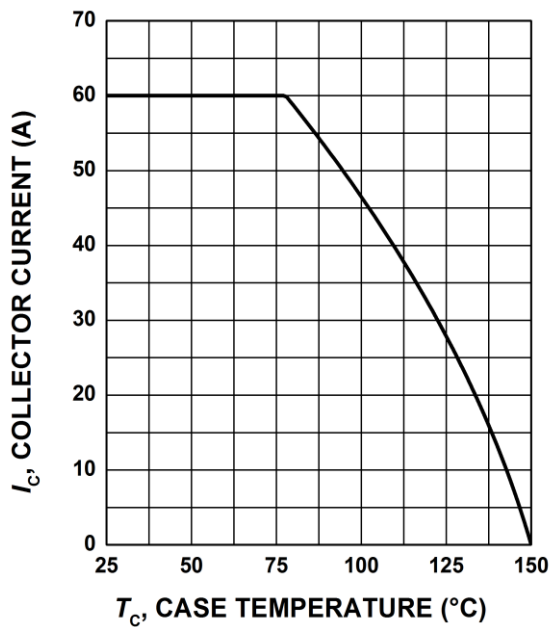


Figure 3. Maximum collector current as a function of case temperature
 $(V_{GE} \geq 15\text{V}, T_j \leq 150^\circ\text{C})$

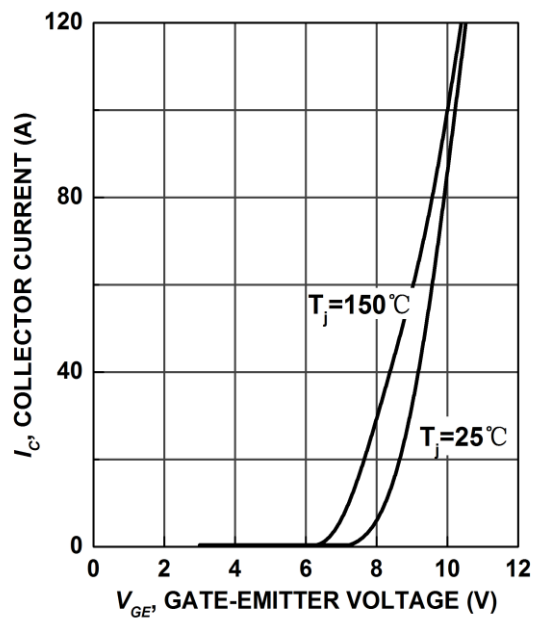


Figure 4. Typical transfer characteristic
 $(V_{CE} = 15\text{V})$

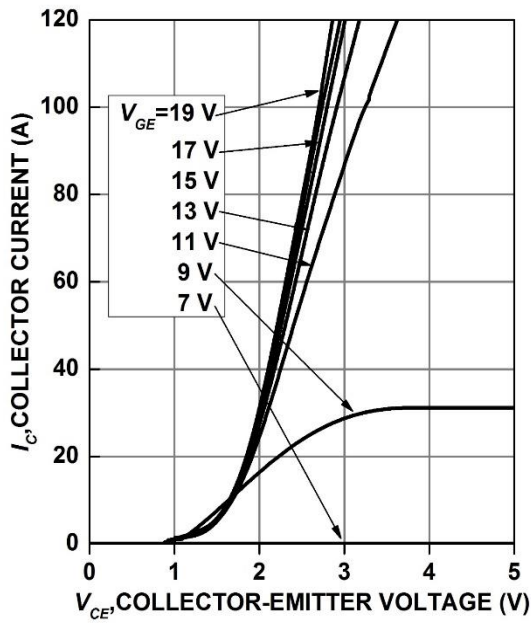


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

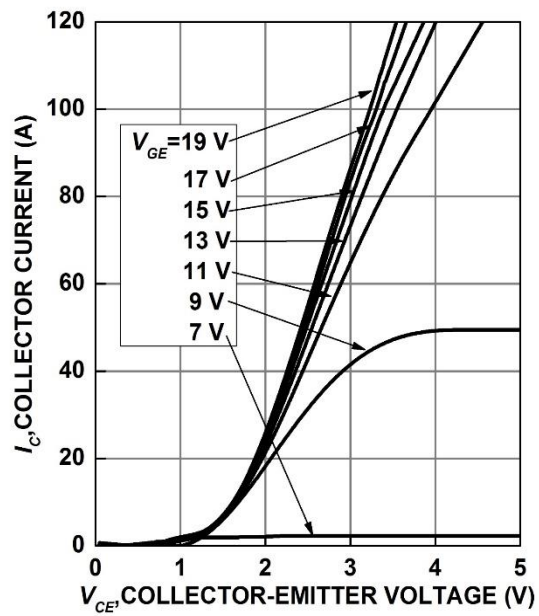


Figure 6. Typical output characteristic
($T_j = 150^\circ\text{C}$)

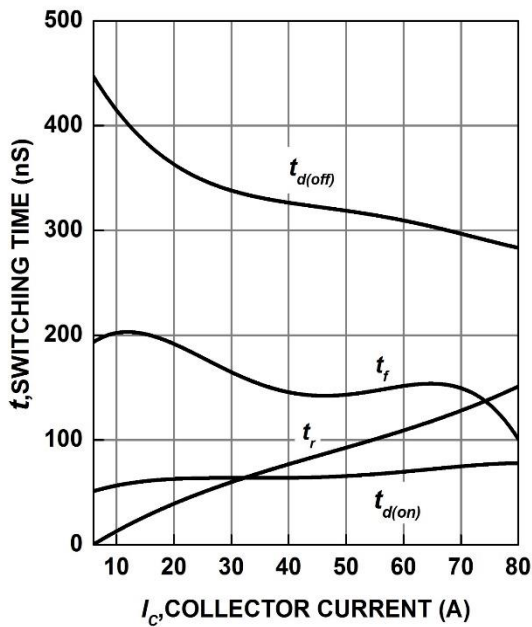


Figure 7. Typical switching times as a function of collector current
(inductive load, $T_j=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=12\Omega$,
Dynamic test circuit in Figure D)

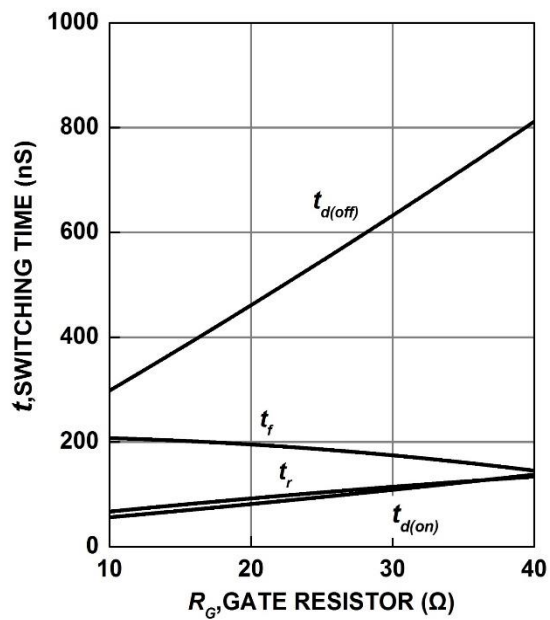


Figure 8. Typical switching times as a function of gate resistor
(inductive load, $T_j=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, Dynamic test circuit in
Figure D)

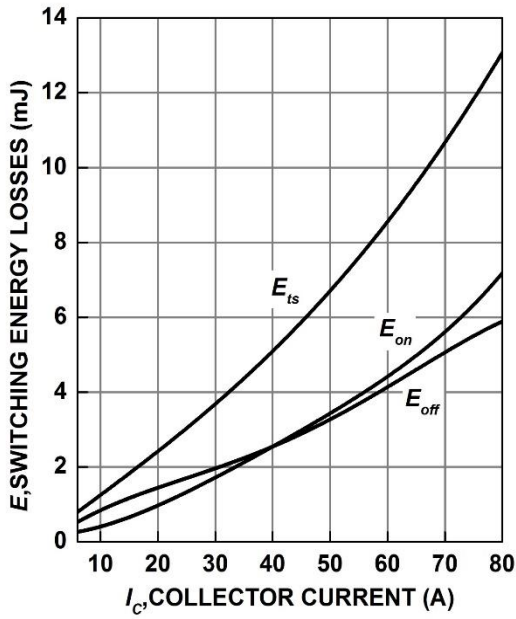


Figure 9. Typical switching energy losses as a function of collector current
(inductive load, $T_j=150^\circ\text{C}$, $V_{CE}=600\text{V}$,
 $V_{GE}=0/15\text{V}$, $R_G=12\Omega$,
Dynamic test circuit in Figure D)

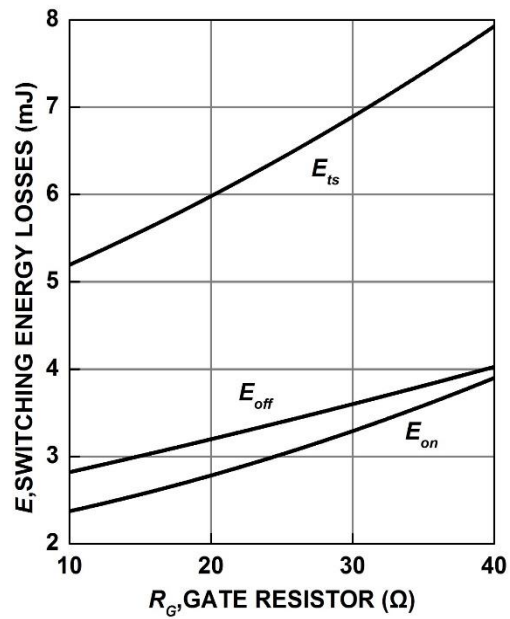


Figure 10. Typical switching energy losses as a function of gate resistor
(inductive load, $T_j=150^\circ\text{C}$, $V_{CE}=600\text{V}$,
 $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$,
Dynamic test circuit in Figure D)

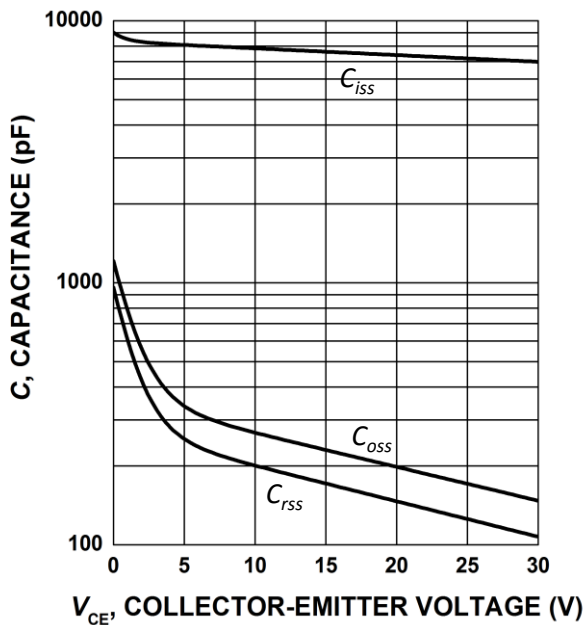


Figure 11. Typical capacitance as a function of collector-emitter voltage
($V_{GE}=0\text{V}$, $f = 1\text{ MHz}$)

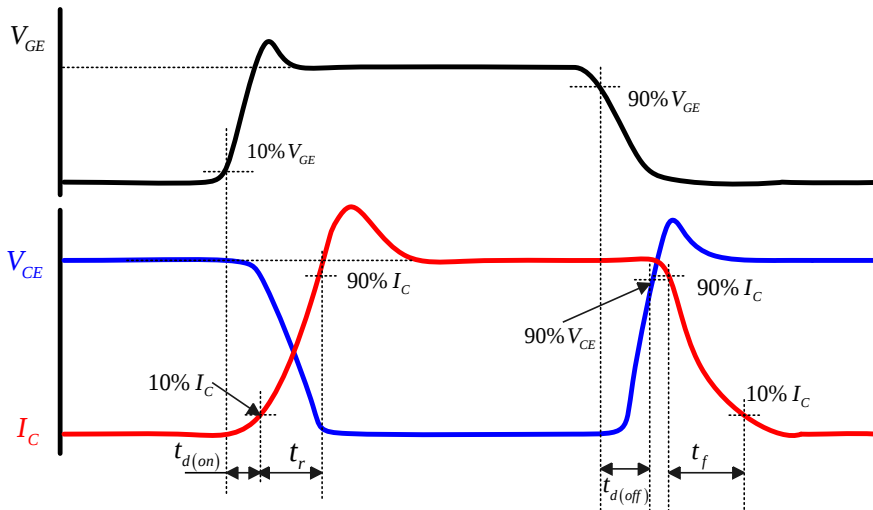


Figure A. Definition of switching times

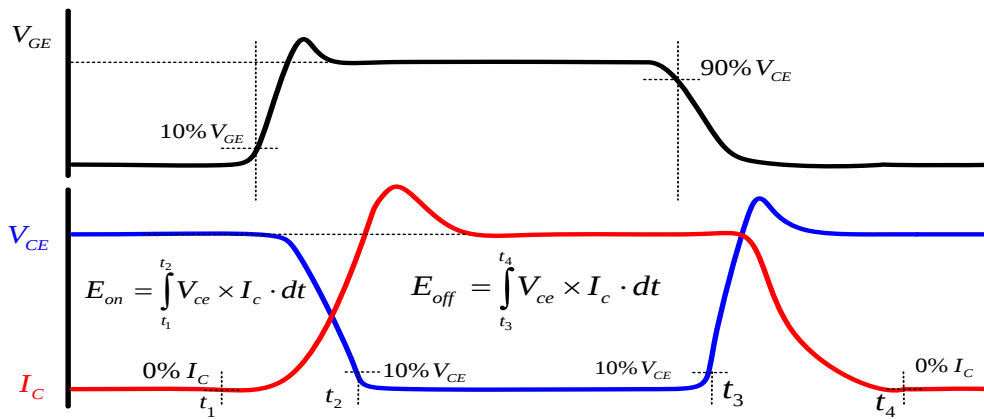


Figure B. Definition of switching losses

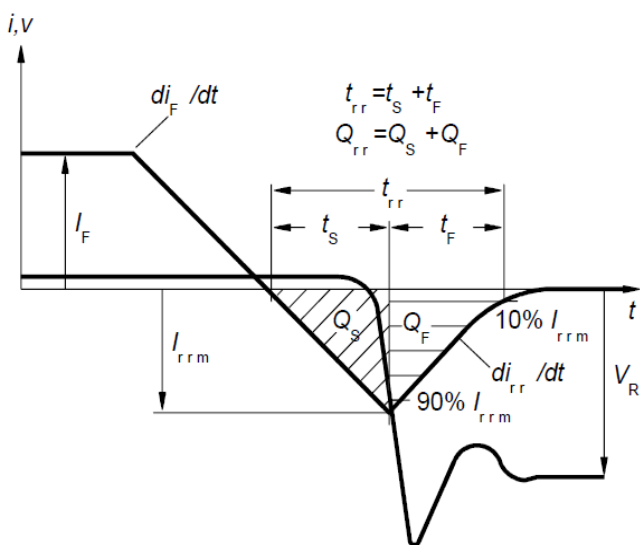


Figure C. Definition of diodes switching characteristics

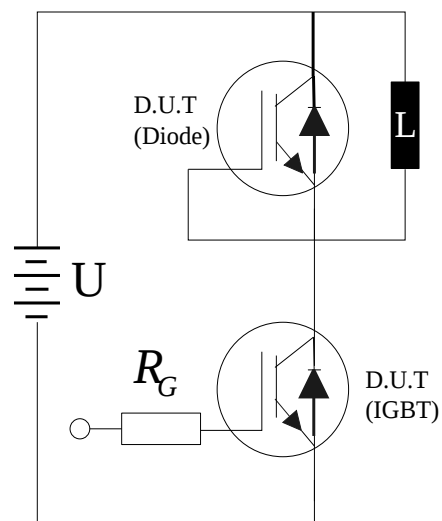
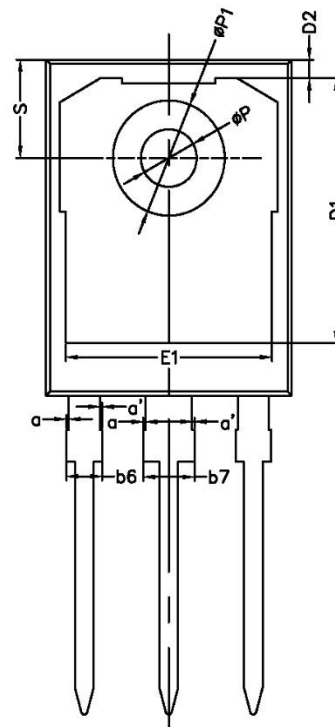
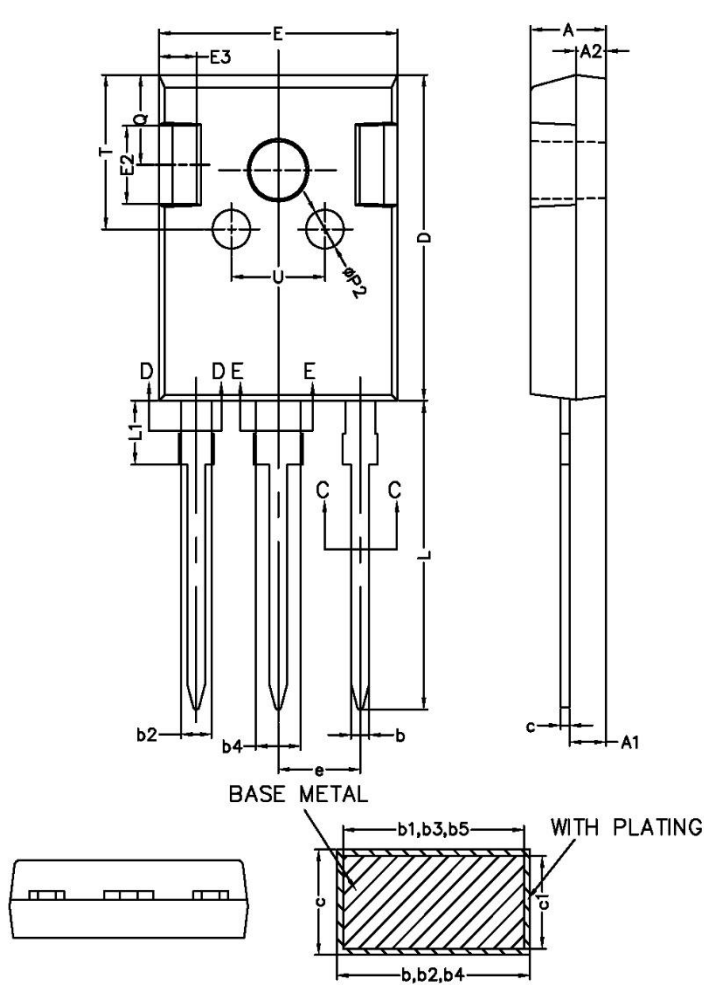


Figure D. Dynamic test circuit

TO-247



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
a	0	—	0.15
a'	0	—	0.15
b	1.16	—	1.26
b1	1.15	1.2	1.22
b2	1.96	—	2.06
b3	1.95	2.00	2.02
b4	2.96	—	3.06
b5	2.95	3.00	3.02
b6	—	—	2.25
b7	—	—	3.25
c	0.59	—	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1	—	—	4.30
P	3.50	3.60	3.70
P1	—	—	7.40
P2	2.40	2.50	2.60
Q	5.60	—	6.00
S	6.05	6.15	6.25
T	9.80	—	10.20
U	6.00	—	6.40

NOTES:
1. ALL DIMENSIONS REFER TO JEDEC STANDARD
TO-247 AD DO NOT INCLUDE MOLD FLASH
OR PROTRUSIONS.
2. EJECTION MARK DEPTH 0.10 ± 0.13